Abstracts

Silicon-based micromachined packages for discrete components

R.M. Henderson and L.P.B. Katehi. "Silicon-based micromachined packages for discrete components." 1997 MTT-S International Microwave Symposium Digest 2. (1997 Vol. II [MWSYM]): 521-524.

A novel approach has been taken to develop low cost, high frequency (Ka-band), electronic packages. An existing thick film package for a phase shifter chip has been redesigned using silicon as the base material. This paper reports on the fabrication techniques and the measurement improvement found by coupling silicon micromachining techniques with standard IC processing.

❑ Return to main document.